

# 32M-Bit (4M X 8/2M X 16) CMOS MASK ROM

#### **FEATURES**

- Switchable organization 4,194,304 x8(byte mode) 2,097,152 x16(word mode)
- Fast access time: 120ns (Max.)
- Supply voltage : single +5V
- Current consumption
  Operating : 60 mA(max.)
  Standby : 50 μA (max.)
- · Fully static operation
- · All inputs and outputs TTL compatible
- · Three state outputs
- Polarity programmable chip enable and output enable pin
- Package
- KM23C32000AG : 44-SOP-600

# **GENERAL DESCRIPTION**

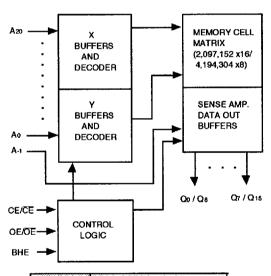
The KM23C32000AG is a fully static mask programmable ROM fabricated using silicon gate CMOS process technology, and is organized either as 4,194,304x8bit(byte mode) or as 2,097,152x16bit(word mode) depending on BHE voltage level.(See mode selection table)

This device operates with a 5V single power supply, and all inputs and outputs are TTL compatible. Because of its asynchronous operation, it requires no external clock assuring extremely easy operation.

It is suitable for use in program memory of microprocessor, and data memory, character generator.

The KM23C32000AG is packaged in a 44-SOP and provides polarity programmable CE and OE buffer as user option mode.

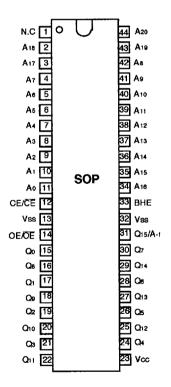
#### FUNCTIONAL BLOCK DIAGRAM



Pin Name	Pin Function
Ao-A20	Address inputs
Q0-Q14	Data Outputs
Q15/A-1	Output 15(Word mode)/
	LSB Address (Byte mode)
BHE	Word/Byte Selection
CE/CE*	Chip Enable
OE/OE*	Output Enable
V∞	Power (+5V)
Vss	Ground
N.C	No Connection

<sup>\*</sup> User Selectable Polarity

#### PIN CONFIGURATION



KM23C32000AG

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### **ABSOLUTE MAXIMUM RATINGS**

		Symbol	Rating	Unit
Voltag	e on Any Pin Relative to Vss	Vin	-0.3 to +7.0	V
Tempe	erature Under Bias	Tbias	-10 to +85	°C
Storag	e Temperature	Tstg	-55 to +150	•C

<sup>\*</sup> Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# RECOMMENDED OPERATING CONDITIONS (Voltage reference to Vss, Ta=0 to 70°C)

ltem	Symbol	Min	Тур	Max	Unit
Supply Voltage	Vcc	4.5	5.0	5.5	V
Supply Voltage	Vss	0	0	0	٧

#### DC CHARACTERISTICS

Parameter		Test Conditions	Min	Max	Unit
Operating Current	lcc	CE=OE=ViL, f=6.7MHz		60	mA
		all outputs open	:		
Standby Current (TTL)	Is <sub>B</sub> 1	CE=Vін, all outputs open	-	1	mA
Standby Current (CMOS)	ISB2	CE=Vcc, all outputs open	-	50	μΑ
Input Leakage Current	lu	Vin=0 to Vcc	-	10	μΑ
Output Leakage Current	llo .	Vouτ=0 to Vcc	-	10	μΑ
Input High Voltage, All Inputs	ViH		2.2	V∞+0.3	V
Input Low Voltage, All Inputs	VIL		-0.3	0.8	V
Output High Voltage Level	Vон	1он= - <b>400</b> <i>µ</i> A	2.4	-	٧
Output Low Voltage Level	Vol	loL= 2.1 mA	-	0.4	٧

# **CAPACITANCE** (Ta=25°C , f=1.0MHz)

Input Capacitance	Cin	VIN = OV	-	12	pF
Output Capacitance	Соит	Vo∪t = 0V	-	12	pF
101 101 10 100 a <b>Item</b> (101 - 100 -		Test Conditions			
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Note: Capacitance is periodically sampled and not 100% tested.

#### MODE SELECTION

CE/CE	OE/OE	ВНЕ	Q15/A-1	Mode	Data	Power
L/H	X	Х	Х	Standby	High-Z	Standby
H/L	L/H	х	X	Operating	High-Z	Active
H/L	H/L	Н	Output	Operating	Qo-Q15:Dout	Active
		L	Input	Operating	Qo-Q7:Dout	Active
					Qe-Q14:High-Z	

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# AC CHARACTERISTICS (TA= 0°C to +70°C, Vcc = 5V ±10%, unless otherwise noted.)

#### **TEST CONDITIONS**

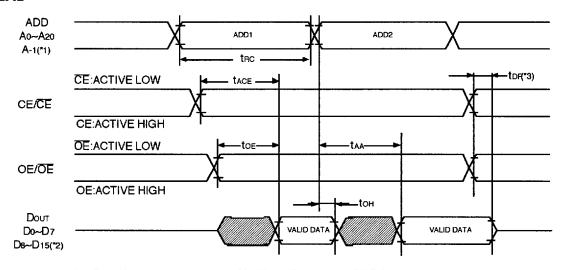
Item	Value
Input Pulse Levels	0.6V to 2.4V
Input Rise and Fall Times	10ns
Input and Output timing Levels	0.8V and 2.0V
Output Loads	1 TTL Gate and C∟=100pF

#### **READ CYCLE**

Parameter	Symbol			KM23C32000AG-15		KM23C32000AG-20		
	Syllido.	Min	Max	Min	Max	Min	Max	Unit
Read Cycle Time	tRC	120		150		200		ns
Chip Enable Access Time	tACE		120		150		200	ns
Address Access Time	tAA		120		150		200	ns
Output Enable Access Time	tOE		60		70		90	ns
Output or Chip Disable to	tDF		20		30		40	ns
Output High-Z								
Output Hold from Address Change	tOH	0		0		0		ns

# **TIMING DIAGRAM**

# **READ**



- (\*1) Byte Mode only. A-1 is Least Significant Bit Address.(BHE=ViL)
- (\*2) Word Mode only (ВНЕ=Vін)
- (\*3) tDF is defined as the time which the outputs achieve the open circuit condition and is not referenced to Voн or VoL level.

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Unit: mm/lnch



# **PACKAGE DIMENSIONS**

# 44 LEAD SMALL OUTLINE PACKAGE

